PicoTrack

semi MEMBER
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309 Laurelwood Rd #21
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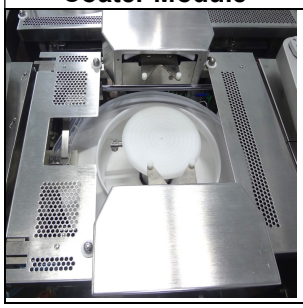
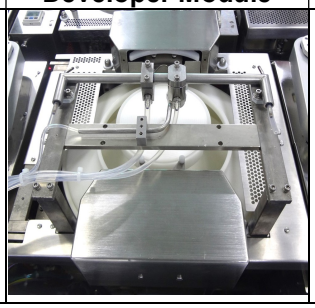
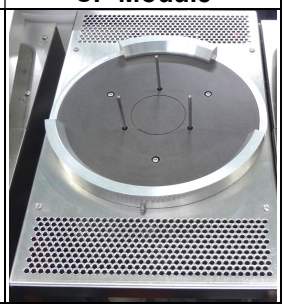
PCT-150RE TRACK SYSTEM

(MASS PRODUCTION WITH 2 TRACKS, 1 COATER, 1 DEVLOPER TOOL SETS)

Please contact Sales sales@picotrack.com for more information

Coater Module	Developer Module	VPO Module	HPO Module	CP Module
				

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Track System Specification	Description
System designed	US Standard System
System Configuration	TRACK 2: SEND - HPO - CP - DEV.(MD.) - HPO - CP- REC TRACK 1: SEND - VPO - CP - COATER - HPO - CP - REC
System dimension	106.50'' length x 35.50'' width x 90'' height
Wafer size (workable dual size)	Up to 6'' (150mm)
Wafer Sensor	Capacity or Optical
Wafer material	Silicon/Sapphire/GaAs/ Ceramic…
System Controller	PC & PLC Controller with Windows OS based
Chemical Cabinet for Developer	Canisters cabinet
Chemical Cabinet for Coater	Photoresist Pumps & Canisters cabinet
Indexer wafer cassette	4, (available upon request)
Robot Arm Transfer Unit	12 Robot Arm
Forearm Arm type	Aluminum clear anodized
System Fan Filter Unit (FFU)	Optional
System Enclosure and windows	Optional
Coater	**1 Module**
Maximum spin speed	6000 rpm
Spin motor	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Dispense arm accuracy	± 0.1 mm
Wafer centering	± 0.1 mm
Dispense arm motion control	Stepper motor and driver
Dispense arm nozzles	3x or more (3/16'' or 1/4'' OD) (Standard)
Dispense method	Static and traverse
Pre-dispense function	Yes
Top/Bottom EBR	Yes
Catch-cup rinse(CCR)	Optional
Cleaning tip nozzle	Optional
Humidity & Temp. control	Optional
Photoresist temperature control	Optional (≤ 1°C , 10-50°C range)
Developer Module	**1 Module**
Maximum spin speed	6000 rpm
Spin motor	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Spin direction	Clockwise (+) & counter clockwise (-)
Dispense arm motion control	Stepper motor and driver
Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm nozzles (STD)	1 Spray+ 1 Stream or 2 sprays+ 2 streams
Developer dispense type	Stream, Puddle, Fan spray, Cone spray….
Dispense method	Static, traverse and sweep
DI water top and back side rinse	Yes
N2 Airing back side	Yes
N2 Blow-off top nozzle	Optional

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Developer fluid temperature control	Optional ≤ 1°C (10-50°C range)
VPO Module	**1 Module**
VPO block type	Aluminum with vacuum slots
VPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	Up to 200°C, Δt: 50°C ≤ 200s
Temperature uniformity	± 10C (25-15°0C), ± 20C (151-200°C)
Prime method	Pressurize N2 with bubbler
Wafer contact angle	≥ 65° on prime silicon wafer
Contact angle uniformmity	≤ 1.5° on prime base silicon wafer
Wafer Carrier	3 pins controlled by stepper motor
Bake method	Proximity, contact, vacuum & purge bake
HPO Module	**3 Modules**
HPO block type	Aluminum anodized with vacuum slots or proximity
Temperature thermal probe	RTD or TC
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature range	25-250°C, Δt: 50°C ≤ 200s, (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer Carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
Chill Plate & Centering	**4 Modules**
Chill Plate block type	Aluminum anodized with vacuum slots
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Wafer Centering	Aluminum anodized centering ring
Wafer Carrier	3 pins controlled by air cylinder
Chill method	contact
Cooling Water Temperature controller	Optional